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(72) Inventors: **Youngon OH**, Hwaseong-si (KR);  
**Youngcheol JANG**, Hwaseong-si (KR);  
**Jihun KIM**, Uiwang-si (KR);  
**Sanghyuk PARK**, Yongin-si (KR);  
**Sangho YOON**, Yongin-si (KR);  
**SeungYeob LEE**, Yongin-si (KR); **Chul**  
**Min LEE**, Changwon-si (KR); **Hochan**  
**LEE**, Seoul (KR); **Jaegyun JEON**,  
Suwon-si (KR); **Jeongkwon JUNG**,  
Anyang-si (KR); **Hyeong Seok CHOO**,  
Suwon-si (KR); **Dongyeol HAN**,  
Pyeongtaek-si (KR)**Publication Classification**(51) **Int. Cl.**  
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A semiconductor fabrication facility including raceways on a ceiling of a structural construction and extending in one direction, a vehicle rail assembly coupled to the raceways, outer jig rails on outer sidewalls of the raceways and adjacent to the vehicle rail assembly, and an outer jig on the outer jig rails and configured to allow the vehicle rail assembly to move along the outer jig rails may be provided.

(73) Assignee: **Samsung Electronics Co., Ltd.,**  
Suwon-si (KR)(21) Appl. No.: **17/894,371**